



		Min.	Typ.	Max.
<b>Collector-Emitter Breakdown Voltage</b> ( $I_C = 10 \mu A, V_{BE} = 0$ )	$V_{(BR)CES}$	40		V
<b>Emitter-Base Breakdown Voltage</b> ( $I_E = 10 \mu A, I_C = 0$ )	$V_{(BR)EBO}$	5		V
<b>Collector-Emitter Saturation Voltage</b> ( $I_C = 150 mA, I_B = 15 mA$ ) ( $I_C = 500 mA, I_B = 50 mA$ )	$V_{CE(sat)} \dagger$ $V_{CE(sat)} \dagger$	.45 1.6	.45 1.6	V V
<b>Base-Emitter Saturation Voltage</b> ( $I_C = 150 mA, I_B = 15 mA$ ) ( $I_C = 500 mA, I_B = 50 mA$ )	$V_{BE(sat)} \dagger$ $V_{BE(sat)} \dagger$	.7 2.6	1.3 2.6	V V
<b>DC Forward Current Transfer Ratio</b> ( $I_C = 1 mA, V_{CE} = 10V$ ) 2N5027 $h_{FE}$ 20 2N5028 $h_{FE}$ 35				
( $I_C = 10 mA, V_{CE} = 10V$ ) 2N5027 $h_{FE} \dagger$ 30 2N5028 $h_{FE} \dagger$ 50				
( $I_C = 150 mA, V_{CE} = 10V$ ) 2N5027 $h_{FE} \dagger$ 50 2N5028 $h_{FE} \dagger$ 100			150 300	
( $I_C = 500 mA, V_{CE} = 10V$ ) 2N5027 $h_{FE} \dagger$ 20 2N5028 $h_{FE} \dagger$ 30				
( $I_C = 150 mA, V_{CE} = 1V$ ) 2N5027 $h_{FE} \dagger$ 20 2N5028 $h_{FE} \dagger$ 40				

### Dynamic Characteristics

<b>Collector-Base Capacitance</b> ( $V_{CB} = 10V, I_E = 0, f = 1 MHz$ )	$C_{cb}$	5	8	pF
<b>Emitter-Base Capacitance</b> ( $V_{EB} = 0.5V, I_C = 0, f = 1 MHz$ )	$C_{eb}$		25	pF
<b>Small Signal Forward Current Transfer Ratio</b> ( $V_{CE} = 10V, I_C = 20 mA, f = 100 MHz$ )	$ h_{fe}  \dagger$	2.5		

†Pulsed operation:  $\leq 300 \mu sec$ , pulse width  $\leq 2\%$  duty cycle

### Switching

Turn-on Delay Time	$t_d$	15	15	
Rise Time	$t_r$	20	30	
Turn-on Time	$t_{on}$	30	40	
Storage Time	$t_s$	35	45	
Fall Time	$t_f$	25	35	
Turn-off Time	$t_{off}$	55	75	

**Figure 1**  
( $I_C = 10 I_{B1} = -10 I_{B2} = 150 mA$ )  
2N5027      2N5028

**Figure 2**  
( $I_C = I_{B1} = -I_{B2} = -20 mA$ )  
2N5027, 8

**Figure 3**  
( $I_C = 10 I_{B1} = -10 I_{B2} = 150 mA$ )  
2N5027, 8

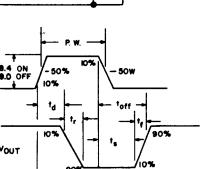
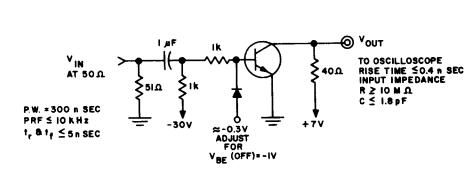
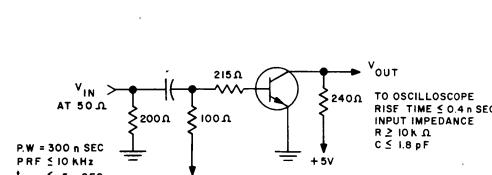
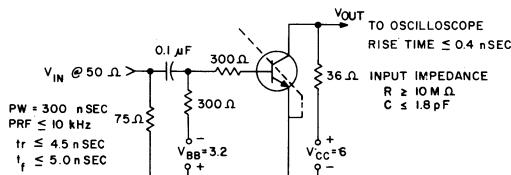


Figure 1.

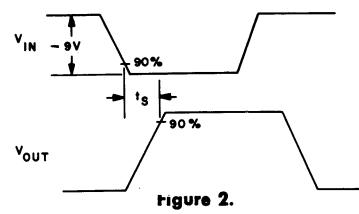


Figure 2.

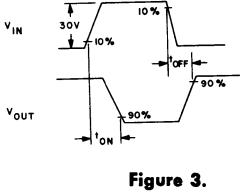


Figure 3.



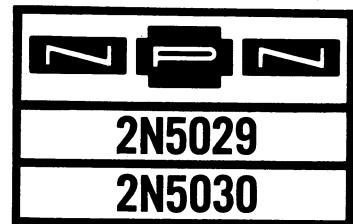
**INNOVATIONS  
IN ACTION**

**SEMICONDUCTORS**

**Silicon**

# Switching Transistors

**PLANAR EPITAXIAL PASSIVATED**



The General Electric 2N5029 and 2N5030 epoxy encapsulated planar epitaxial passivated NPN Silicon Transistors are designed primarily for high speed industrial switchings. They are electrically similar to the 2N2368 and 2N2369. These devices are also available in an equivalent TO-5 or TO-18 pin configuration.

**Features:**  

- Low Cost
- High Speed

**Environmental Performance Comparable to Hermetic**

**absolute maximum ratings: (25°C) (unless otherwise specified)**

**Voltages**

		<b>2N5029</b>	<b>2N5030</b>	
Collector to Base	$V_{CBO}$	40	30	V
Emitter to Base	$V_{EBO}$	4.5	4.0	V
Collector to Emitter	$V_{CEO}$	15	12	V
Collector to Emitter	$V_{CES}$	40	30	V

**Currents**

Collector (Steady State)	$I_C$	200	200	mA
Collector (pulsed, peak, 10 $\mu$ sec. 2% duty cycle)	$I_C$	500	500	mA

**Dissipation**

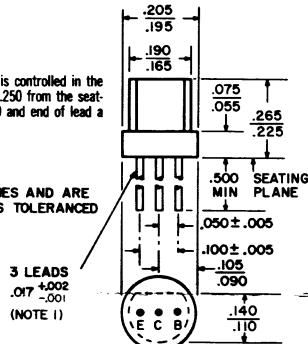
Total Power (Free Air at 25°C)*	$P_T$	320	320	mW
Total Power (Free Air at 65°C)*	$P_T$	185	185	mW

**Temperature**

Storage	$T_S$	-65 to +150	°C	
Operating Junction	$T_J$	-65 to +120	°C	
Lead ( $\frac{1}{16}'' \pm \frac{1}{32}''$ from case for 10 seconds).	$T_L$	260	260	°C

NOTE 1: Lead diameter is controlled in the zone between .070 and .250 from the seating plane. Between .250 and end of lead a max. of .021 is held.

ALL DIMEN. IN INCHES AND ARE  
REFERENCE UNLESS TOLERANCED  
TO -98



\*Derate 3.4 mW/°C for increase in ambient temperature between 25 and 120°C.

**electrical characteristics: (25°C) (unless otherwise specified)**

			<b>2N5029</b>	<b>2N5030</b>				
<b>Static Characteristics</b>			Min.	Typ.	Max.	Min.	Typ.	Max.
<b>Emitter-Base Reverse Current</b> ( $V_{EB} = 3V$ , $I_C = 0$ )	$I_{EBO}$				20			50 nA
<b>Collector Reverse Current</b> ( $V_{CE} = 20V$ ) ( $V_{CE} = 20V$ , $T_A = 70^\circ C$ )	$I_{CES}$		250			250	nA	
$I_{CES}$			4.0			4.0	$\mu A$	
<b>Collector-Base Breakdown Voltage</b> ( $I_C = 10\mu A$ , $I_E = 0$ )	$V_{(BR)CBO}$	40			30			V
<b>Collector-Emitter Breakdown Voltage</b> ( $I_C = 10mA$ , $I_B = 0$ )	$V_{(BR)CEO}^{\dagger}$	15			12			V
<b>Collector-Emitter Breakdown Voltage</b> ( $I_C = 10\mu A$ )	$V_{(BR)CES}$	40			30			V
<b>Emitter-Base Breakdown Voltage</b> ( $I_E = 10\mu A$ , $I_C = 0$ )	$V_{(BR)EBO}$	4.5			4.0			V

	2N5029			2N5030		
	Min.	Typ.	Max.	Min.	Typ.	Max.
<b>Collector-Emitter Saturation Voltage</b> ( $I_C = 10\text{mA}$ , $I_B = 1\text{mA}$ )		$V_{CE(\text{sat})} \dagger$		0.25		0.25 V
<b>Base-Emitter Saturation Voltage</b> ( $I_C = 10\text{mA}$ , $I_B = 1\text{mA}$ )		$V_{BE(\text{sat})} \dagger$	0.72	0.87	0.72	0.87 V
<b>Static Forward Current Transfer Ratio</b> ( $I_C = 10\text{mA}$ , $V_{CE} = 1\text{V}$ ) ( $I_C = 100\text{mA}$ , $V_{CE} = 2.0\text{V}$ )		$h_{FE} \dagger$	40 20	120	30	

†Pulsed operation:  $\leq 300 \mu\text{sec}$  plus width,  $\leq 2\%$  duty cycle

### Dynamic Characteristics

<b>Collector-Base Capacitance</b> ( $V_{CB} = 10\text{V}$ , $I_E = 0$ , $f = 1\text{MHz}$ )	$C_{cb}$		4	4 pF
<b>Emitter-Base Capacitance</b> ( $V_{EB} = 0.5\text{V}$ , $I_C = 0$ , $f = 1\text{MHz}$ )	$C_{eb}$		5	5 pF
<b>Small Signal Forward Current Transfer Ratio</b> ( $V_{CE} = 10\text{mA}$ , $I_C = 10\text{mA}$ , $f = 100\text{MHz}$ )	$ h_{fe} $	5	4	

### Switching (See Figure 1)

$(I_C = 10\text{mA}, I_{B1} = 1.0\text{mA}, I_{B2} = 1\text{mA})$				
Turn-on Delay Time	$t_d$	.10	10	nsec
Rise Time	$t_r$	12	14	nsec
Turn-on Time	$t_{on}$	20	22	nsec
Storage Time	$t_s$	12	14	nsec
Fall Time	$t_f$	14	16	nsec
Turn-off Time	$t_{off}$	24	28	nsec

### Typical Operation in 2N2368-9 Test Circuits

<b>Turn-on Time</b> ( $I_C = 10\text{mA}$ , $I_{B1} = 3\text{mA}$ , $I_{B2} = -1.5\text{mA}$ )	$t_{on}$	12	12	nsec
<b>Storage Time</b> ( $I_C = I_{B1} = I_{B2} = 10\text{mA}$ )	$t_s$	14	14	nsec
<b>Turn-off Time</b> ( $I_C = 10\text{mA}$ , $I_{B1} = 3\text{mA}$ , $I_{B2} = -1.5\text{mA}$ )	$t_{off}$	8	8	nsec

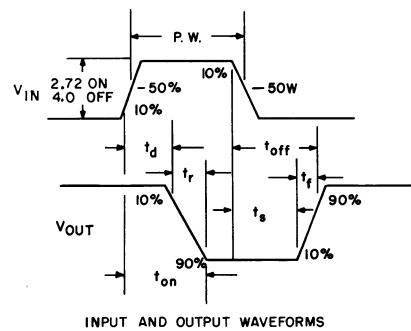
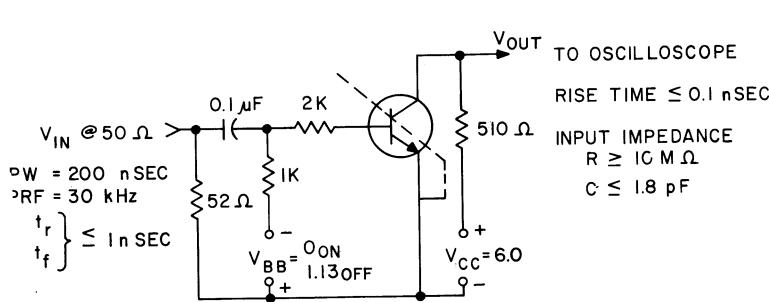


Figure 1.

Printed in U.S.A.